
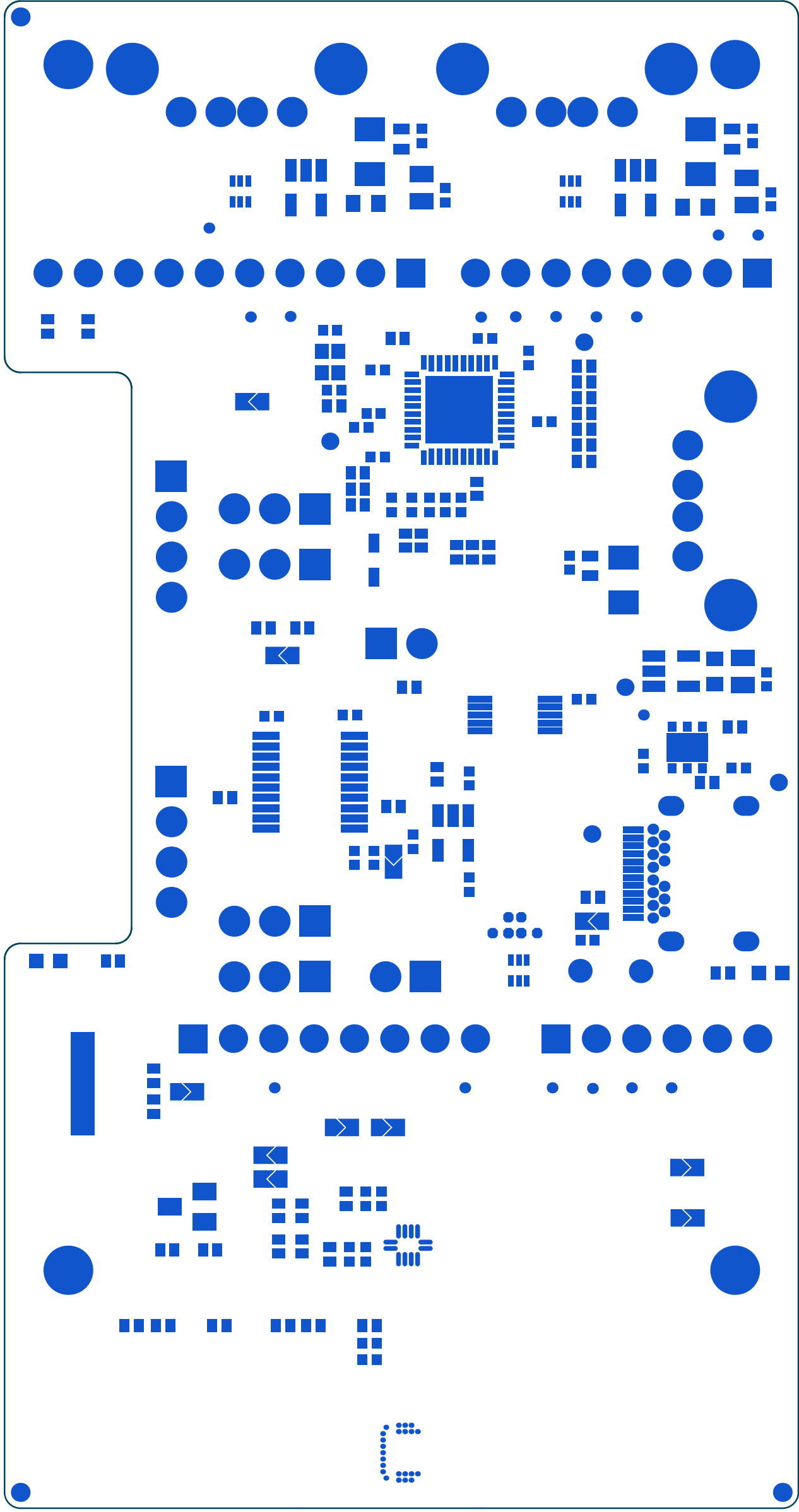

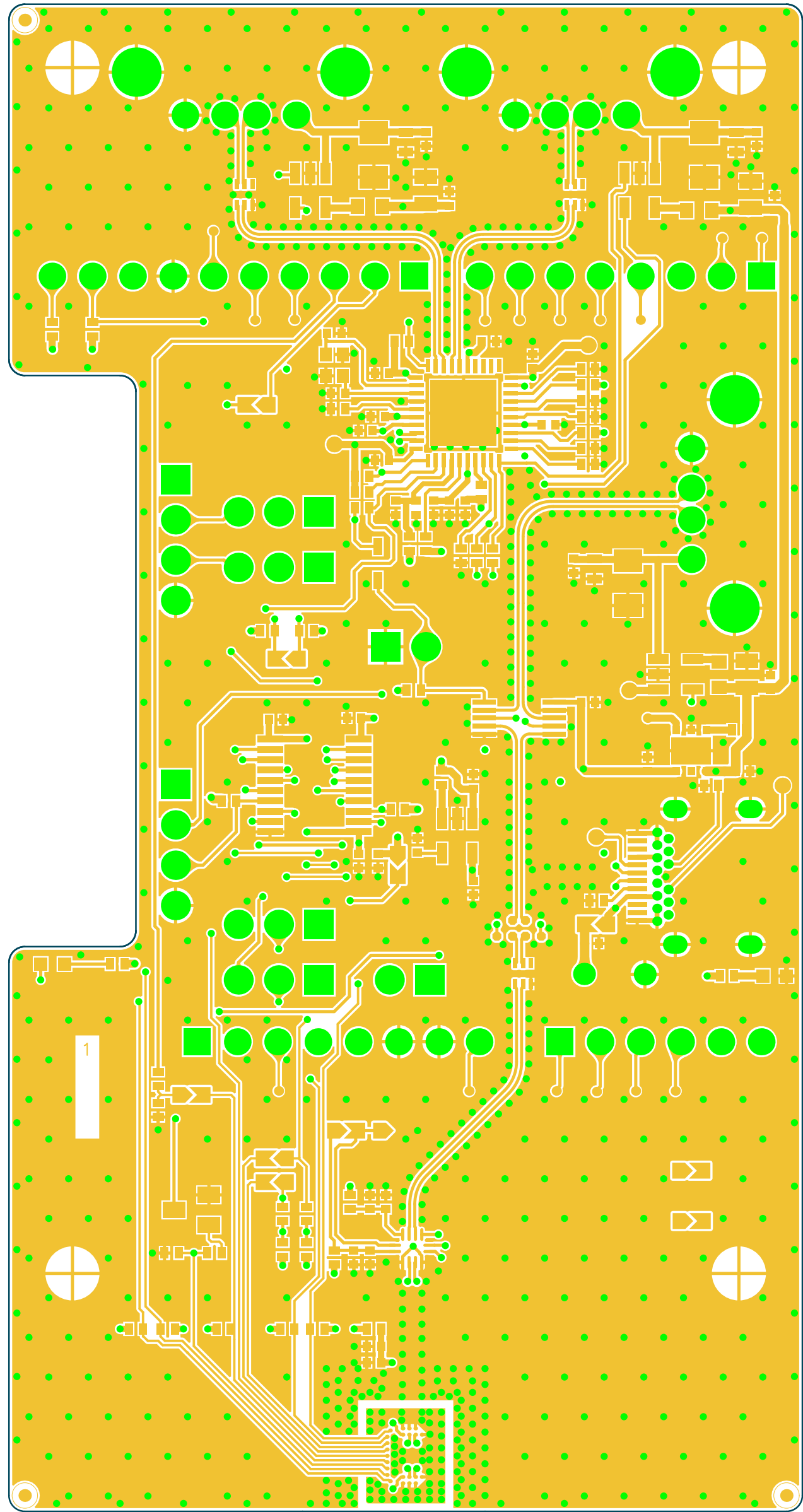



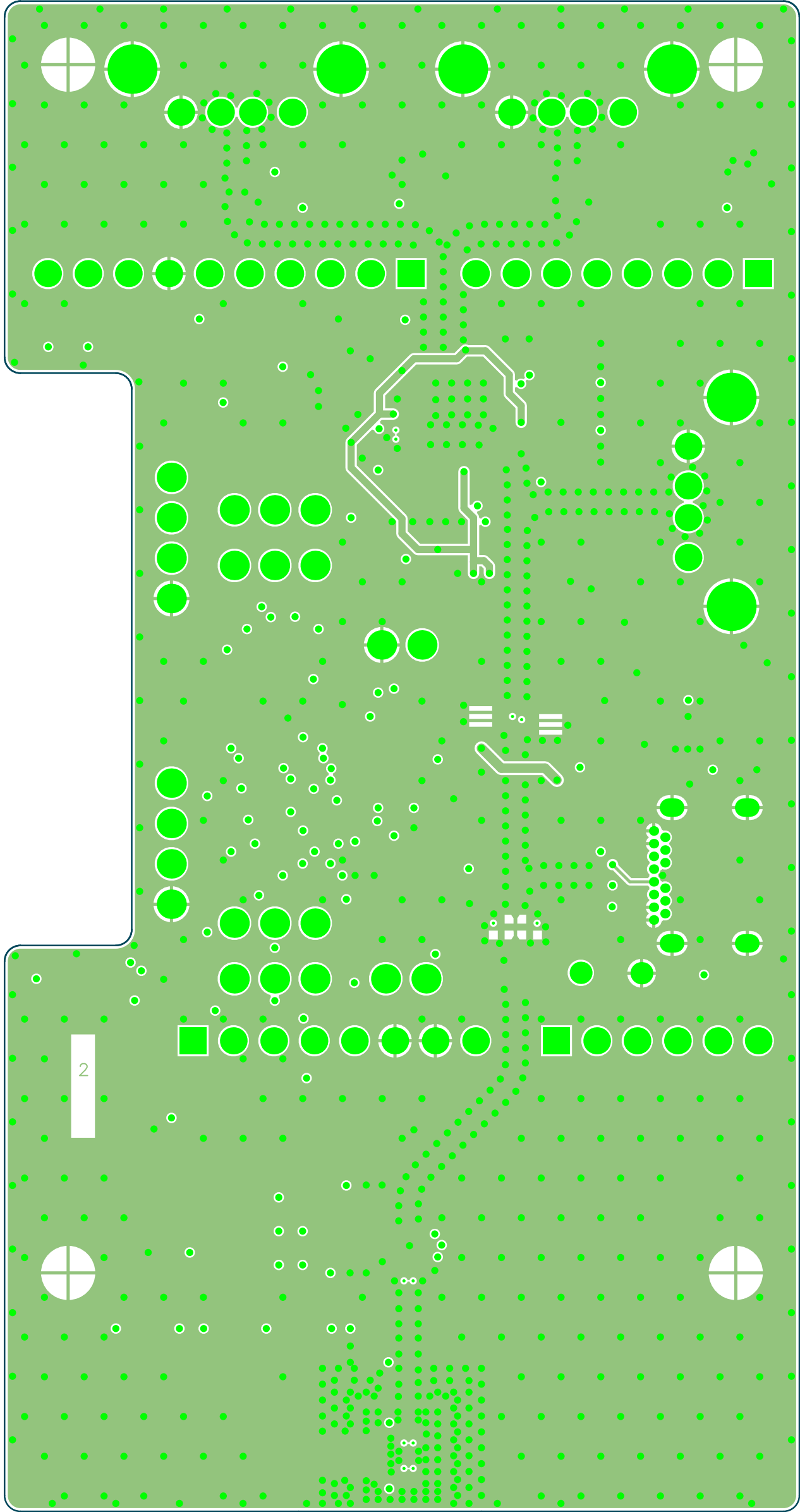
Project: ST60A3H1 Xnucleo (USB2/I2C/UART)		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	B2379	
Date: 2nd February 2024	Rev: A	




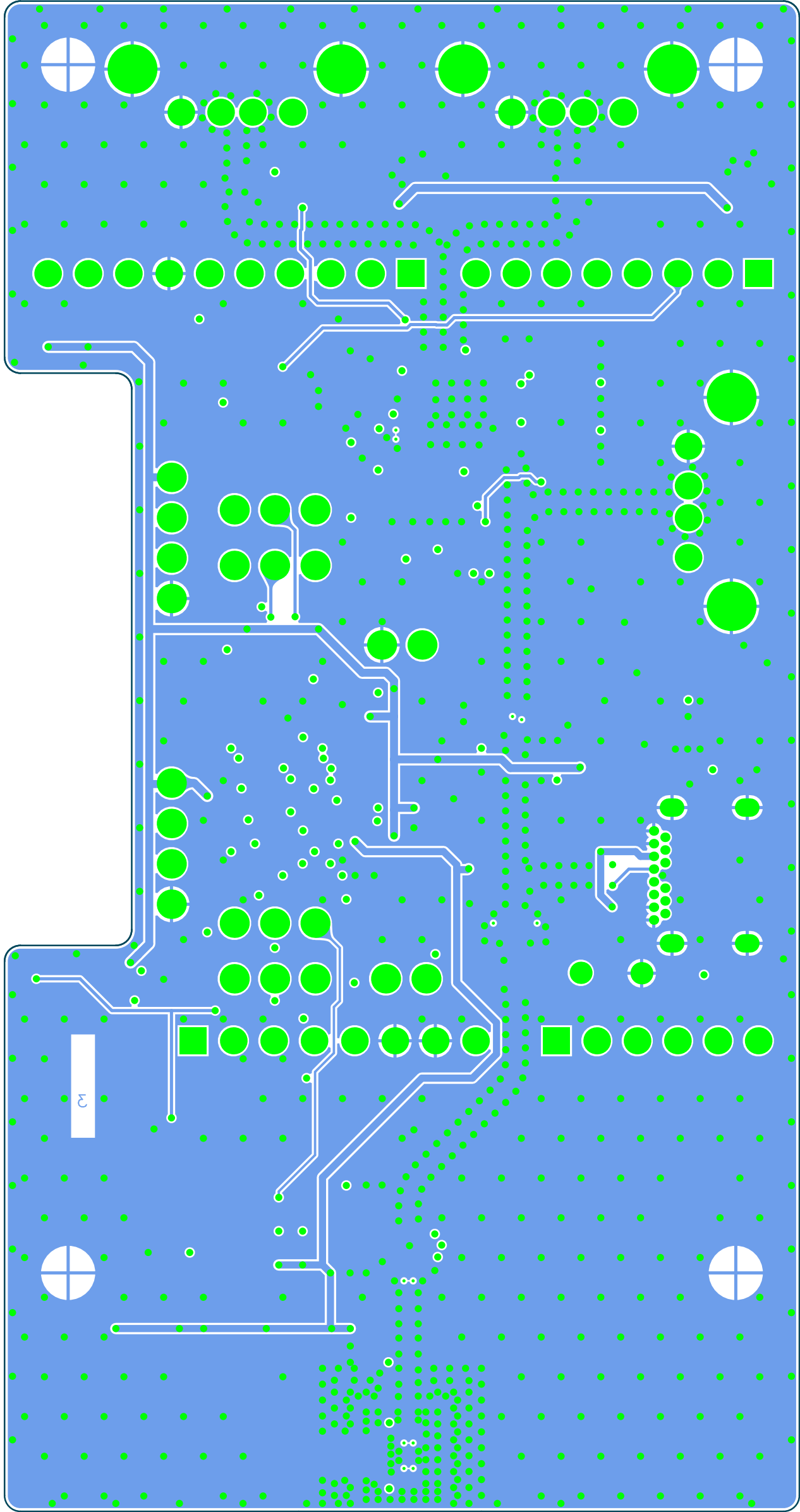
Project: ST60A3H1 Xnucleo (USB2/I2C/UART)		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	B2379	
Date: 2nd February 2024	Rev: A	




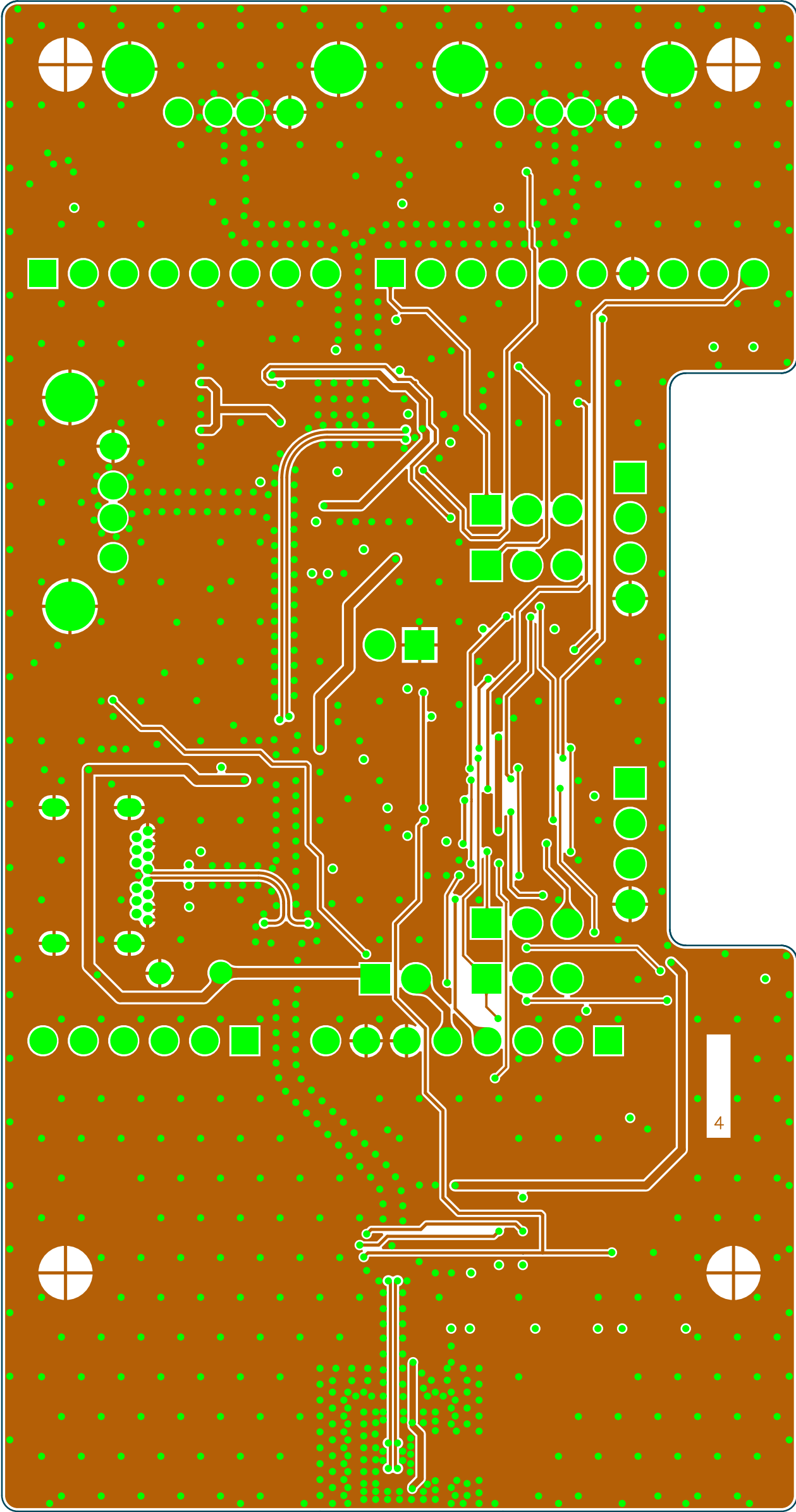
Project: ST60A3H1 Xnucleo (USB2/I2C/UART)		
Layer: Top Layer 1 Signal	Gerber: .GTL	
Variant: [No Variations]	B2379	
Date: 2nd February 2024	Rev: A	




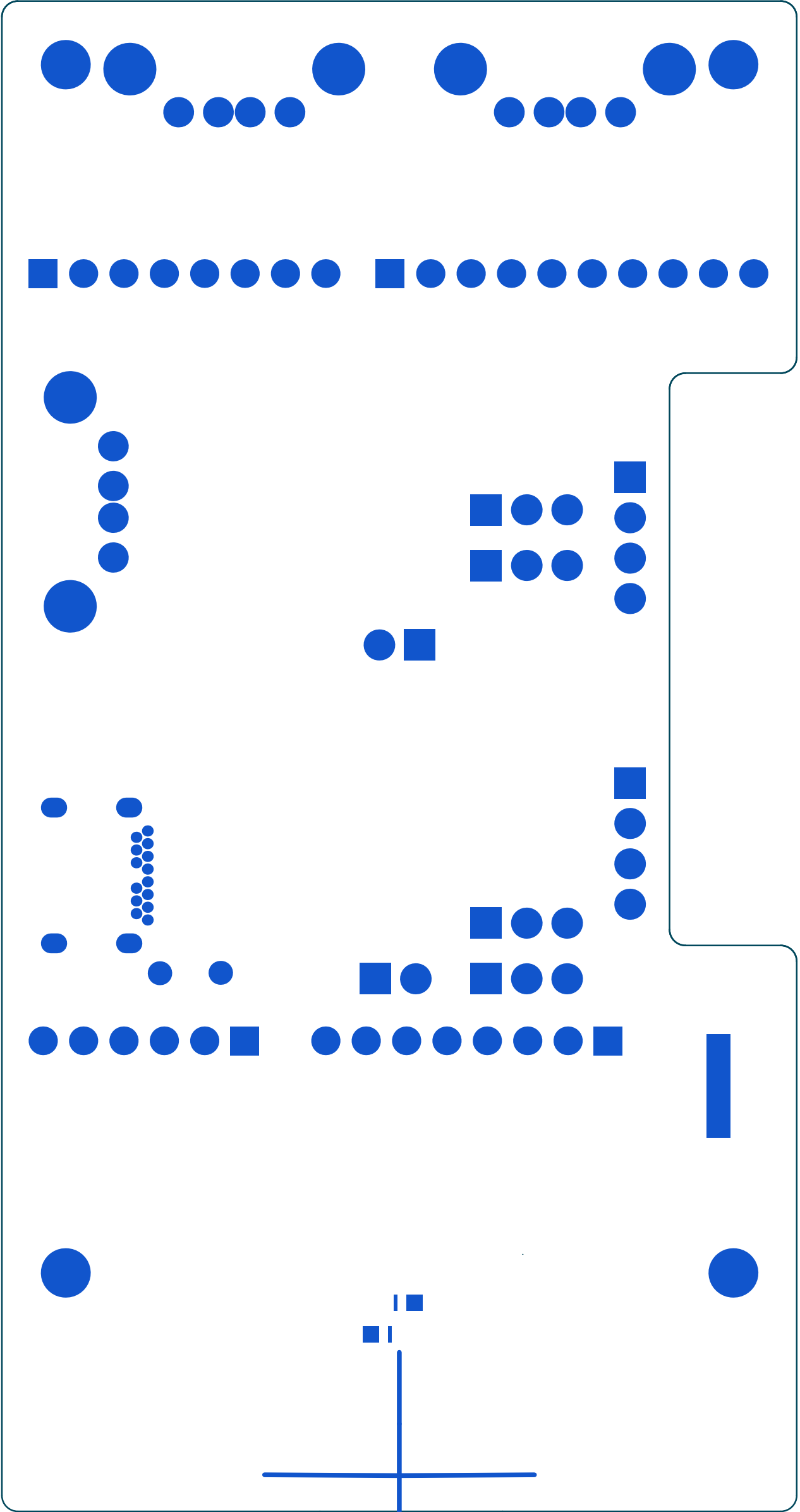
Project: ST60A3H1 Xnucleo (USB2/I2C/UART)		
Layer: Layer 2	Gerber: .G1	
Variant: [No Variations]	B2379	
Date: 2nd February 2024	Rev: A	




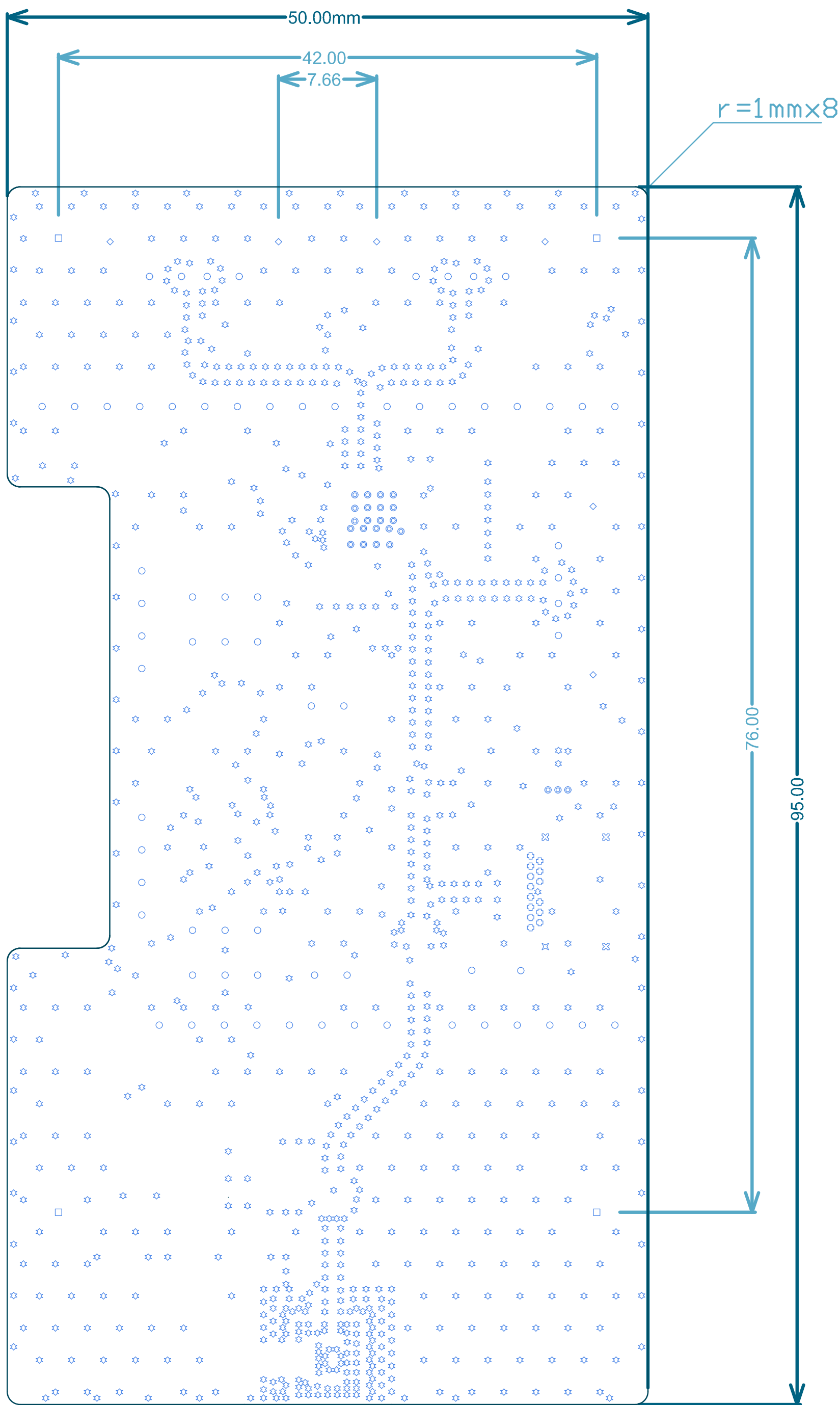
Project: ST60A3H1 Xnucleo (USB2/I2C/UART)		
Layer: Layer 3	Gerber: .G2	
Variant: [No Variations]	B2379	
Date: 2nd February 2024	Rev: A	



Project: ST60A3H1 Xnucleo (USB2/I2C/UART)		
Layer: Bottom Layer 4 Signal	Gerber: .GBL	
Variant: [No Variations]	B2379	
Date: 2nd February 2024	Rev: A	



Project: ST60A3H1 Xnucleo (USB2/I2C/UART)		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	B2379	
Date: 2nd February 2024	Rev: A	



« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☒ ECU104

☐ TG-170

☐ TG-150

☐ TG-140

☐ TG-155

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☐ WHITE

☐ RED

☒ Blue ink PANTONE 2955

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

☐ Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

**Plating type :

lead Gold

AREL	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-003	1.00mil	4	
1	Top Layer 1 Signal	Cu EXT	1.38mil		
	Dielectric 1	2 x 7628	14.17mil	4.6	
2	Layer 2	CF-004	0.71mil		
	Core	CORE- 6 X 7628M	27.95mil	4.4	
3	Layer 3	CF-004	0.71mil		
	Dielectric 2	2 x 7628	14.17mil	4.6	
4	Bottom Layer 4 Signal	Cu EXT	1.38mil		
	Bottom Solder	SM-003	1.00mil	4	
	Bottom Overlay				

Total board thickness: 62.47mil

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (-)	Hole Length	Routed Path Length	Via Feature	Via Type
⚙	945	0.200mm (7.87mil)	PTH	Round	Top Layer 1 Signal - Bottom Layer 4 Signal	Via	Rounded	(Mixed)	(Mixed)		-	-		
⦿	24	0.200mm (7.87mil)	PTH	Round	Top Layer 1 Signal - Bottom Layer 4 Signal	Via	Rounded	v45h20m-45mx0			-	-	Filling Both, Capping Both	Type 7
⊕	14	0.400mm (15.75mil)	PTH	Round	Top Layer 1 Signal - Bottom Layer 4 Signal	Pad	Rounded	c60h40m70			-	-		
⊗	3	0.450mm (17.72mil)	PTH	Slot	Top Layer 1 Signal - Bottom Layer 4 Signal	Pad	Rounded	r155_115h45_85r57m165_125(Tol-5)		0.050mm (1.97mil)	0.850mm (33.47mil)	0.400mm (15.75mil)		
⊗	1	0.450mm (17.72mil)	PTH	Slot	Top Layer 1 Signal - Bottom Layer 4 Signal	Pad	Rounded	r155_115h45_85r57m165_125			0.850mm (33.47mil)	0.400mm (15.75mil)		
◯	70	1.000mm (39.37mil)	PTH	Round	Top Layer 1 Signal - Bottom Layer 4 Signal	Pad	(Mixed)	(Mixed)			-	-		
◊	6	2.400mm (94.49mil)	PTH	Round	Top Layer 1 Signal - Bottom Layer 4 Signal	Pad	Rounded	c310h240m330			-	-		
◻	4	3.000mm (118.11mil)	PTH	Round	Top Layer 1 Signal - Bottom Layer 4 Signal	Pad	Rounded	c0h300m310			-	-		
	1067 Total													

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: ST60A3H1 Xnucleo (USB2/I2C/UART)	
Layer: M2 Board Dimensions	
Variant: [No Variations]	
Date: 2nd February 2024	
Gerber: .GMI2	
B2379	
Rev: A	